

## MOSFET

Metal Oxide Semiconductor Field Effect Transistor

## OptiMOS™ Power-Transistor, 100V

OptiMOS™3 Power-Transistor  
IPA086N10N3 G

## Data Sheet

Rev. 2.4  
Final

**OptiMOS™3 Power-Transistor**
**Features**

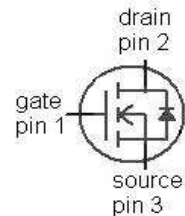
- N-channel, normal level
- Excellent gate charge x  $R_{DS(on)}$  product (FOM)
- Very low on-resistance  $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating; RoHS compliant
- Qualified according to JEDEC<sup>1)</sup> for target application
- Ideal for high-frequency switching and synchronous rectification
- Halogen-free according to IEC61249-2-21
- Fully isolated package (2500 VAC; 1 minute)

**Product Summary**

$V_{DS}$	100	V
$R_{DS(on),max}$	8.6	mΩ
$I_D$	45	A



<b>Type</b>	IPA086N10N3 G
<b>Package</b>	PG-TO220-FP
<b>Marking</b>	086N10N



**Maximum ratings**, at  $T_j=25\text{ °C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	$I_D$	$T_C=25\text{ °C}^{2)}$	45	A
		$T_C=100\text{ °C}$	32	
Pulsed drain current <sup>2)</sup>	$I_{D,pulse}$	$T_C=25\text{ °C}$	180	
Avalanche energy, single pulse	$E_{AS}$	$I_D=45\text{ A}$ , $R_{GS}=25\text{ }\Omega$	170	mJ
Gate source voltage	$V_{GS}$		$\pm 20$	V
Power dissipation	$P_{tot}$	$T_C=25\text{ °C}$	37.5	W
Operating and storage temperature	$T_j$ , $T_{stg}$		-55 ... 175	°C
IEC climatic category; DIN IEC 68-1			55/175/56	

<sup>1)</sup> J-STD20 and JESD22

<sup>2)</sup> See figure 3

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
<b>Thermal characteristics</b>						
Thermal resistance, junction - case	$R_{thJC}$		-	-	4	K/W

**Electrical characteristics**, at  $T_j=25\text{ °C}$ , unless otherwise specified

### Static characteristics

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}, I_D=1\text{ mA}$	100	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=75\text{ }\mu\text{A}$	2	2.7	3.5	
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=100\text{ V}, V_{GS}=0\text{ V}, T_j=25\text{ °C}$	-	0.1	1	$\mu\text{A}$
		$V_{DS}=100\text{ V}, V_{GS}=0\text{ V}, T_j=125\text{ °C}$	-	10	100	
Gate-source leakage current	$I_{GSS}$	$V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$	-	1	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10\text{ V}, I_D=45\text{ A}$	-	7.5	8.6	m $\Omega$
		$V_{GS}=6\text{ V}, I_D=23\text{ A}$	-	9.2	15.4	
Gate resistance	$R_G$		-	1.4	-	$\Omega$
Transconductance	$g_{fs}$	$ V_{DS} >2 I_D R_{DS(on)max}, I_D=45\text{ A}$	35	69	-	S

<sup>3)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70  $\mu\text{m}$  thick) copper area for drain connection. PCB is vertical in still air.

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

**Dynamic characteristics**

Input capacitance	$C_{iss}$	$V_{GS}=0\text{ V}, V_{DS}=50\text{ V},$ $f=1\text{ MHz}$	-	2990	3980	pF
Output capacitance	$C_{oss}$		-	523	696	
Reverse transfer capacitance	$C_{rss}$		-	21	-	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=50\text{ V}, V_{GS}=10\text{ V},$ $I_D=45\text{ A}, R_{G,ext}=1.6\ \Omega$	-	16	-	ns
Rise time	$t_r$		-	10	-	
Turn-off delay time	$t_{d(off)}$		-	27	-	
Fall time	$t_f$		-	8	-	

**Gate Charge Characteristics<sup>4)</sup>**

Gate to source charge	$Q_{gs}$	$V_{DD}=50\text{ V}, I_D=45\text{ A},$ $V_{GS}=0\text{ to }10\text{ V}$	-	14	-	nC
Gate to drain charge	$Q_{gd}$		-	8	-	
Switching charge	$Q_{sw}$		-	13	-	
Gate charge total	$Q_g$		-	42	55	
Gate plateau voltage	$V_{plateau}$		-	4.6	-	
Output charge	$Q_{oss}$	$V_{DD}=50\text{ V}, V_{GS}=0\text{ V}$	-	55	73	nC

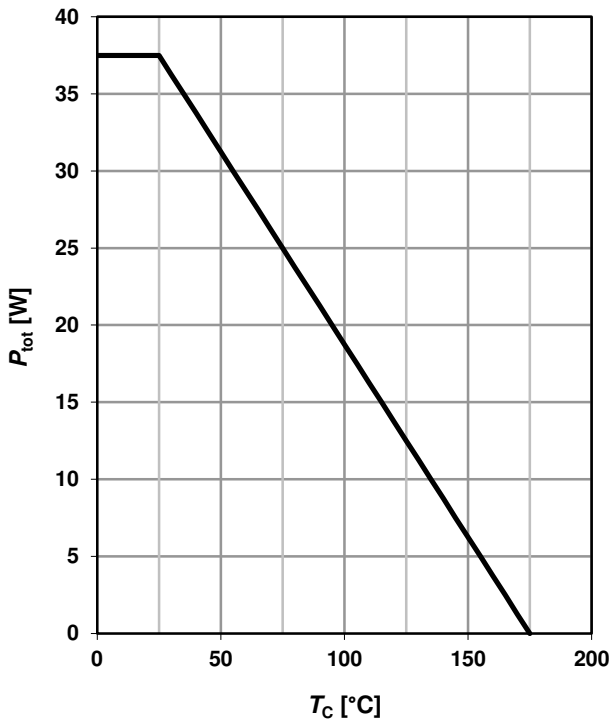
**Reverse Diode**

Diode continuous forward current	$I_S$	$T_C=25\text{ °C}$	-	-	45	A
Diode pulse current	$I_{S,pulse}$		-	-	180	
Diode forward voltage	$V_{SD}$	$V_{GS}=0\text{ V}, I_F=45\text{ A},$ $T_j=25\text{ °C}$	-	0.9	1.2	V
Reverse recovery time	$t_{rr}$	$V_R=50\text{ V}, I_F=45\text{ A},$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	63	-	ns
Reverse recovery charge	$Q_{rr}$		-	120	-	nC

<sup>4)</sup> See figure 16 for gate charge parameter definition

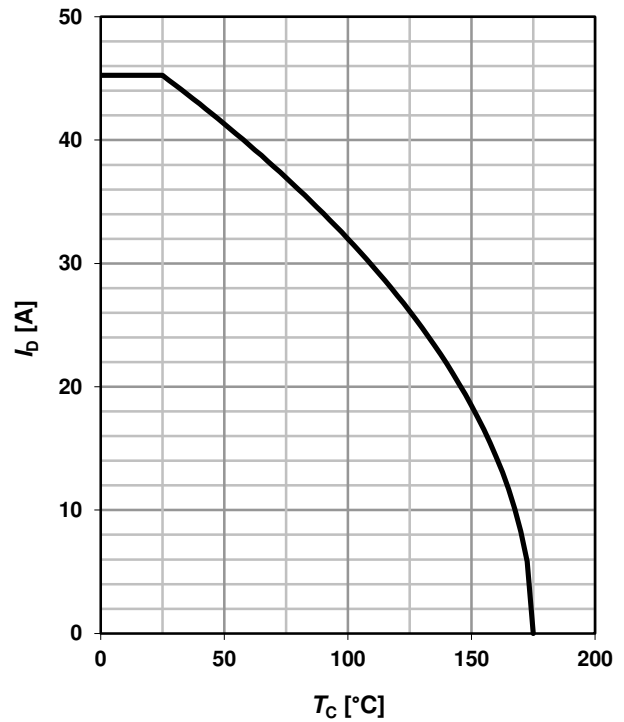
**1 Power dissipation**

$P_{tot}=f(T_C)$



**2 Drain current**

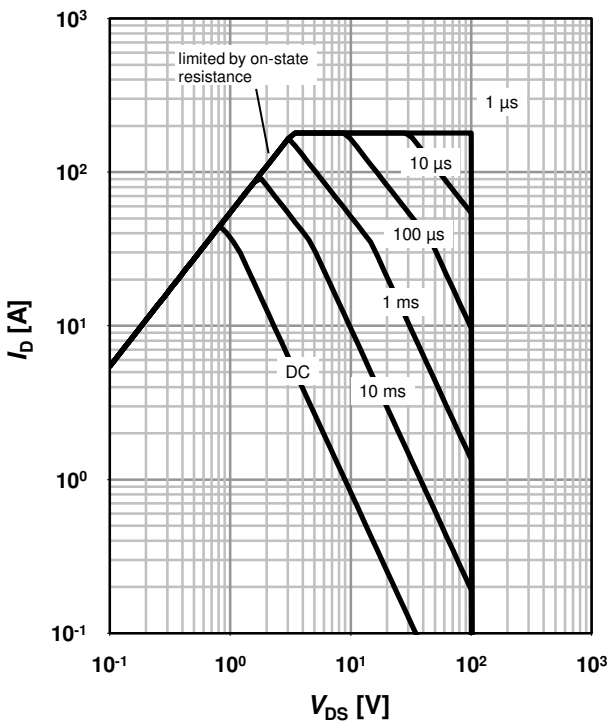
$I_D=f(T_C); V_{GS} \geq 10\text{ V}$



**3 Safe operating area**

$I_D=f(V_{DS}); T_C=25\text{ °C}; D=0$

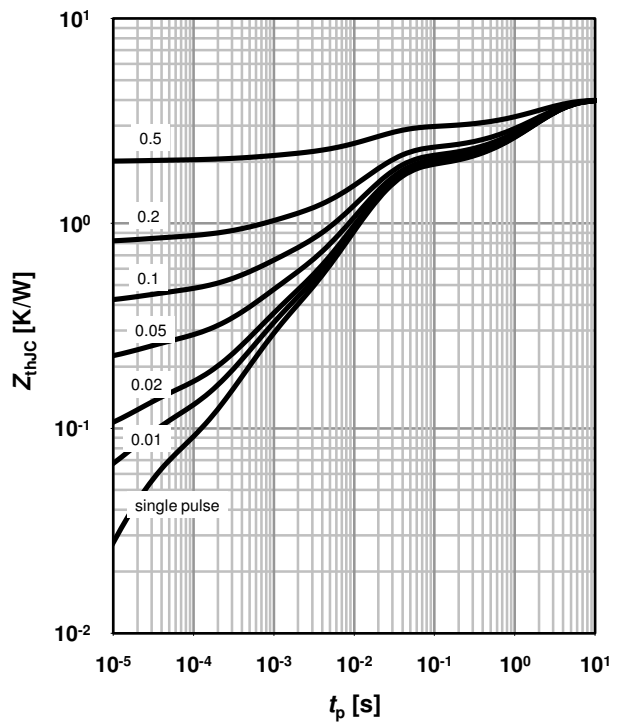
parameter:  $t_p$



**4 Max. transient thermal impedance**

$Z_{thJC}=f(t_p)$

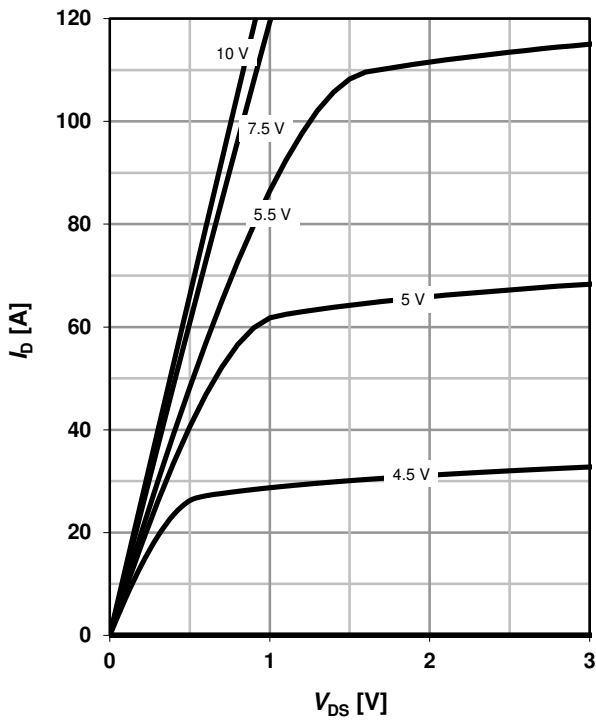
parameter:  $D=t_p/T$



**5 Typ. output characteristics**

$I_D=f(V_{DS}); T_j=25\text{ }^\circ\text{C}$

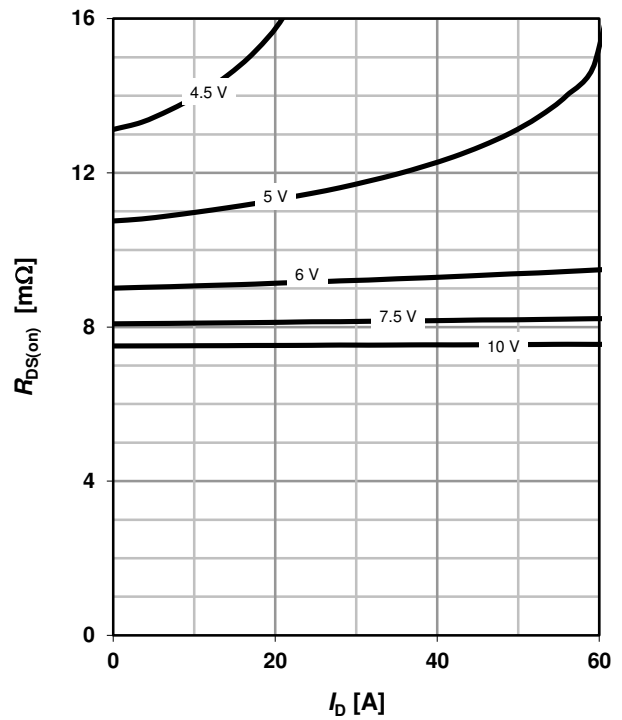
parameter:  $V_{GS}$



**6 Typ. drain-source on resistance**

$R_{DS(on)}=f(I_D); T_j=25\text{ }^\circ\text{C}$

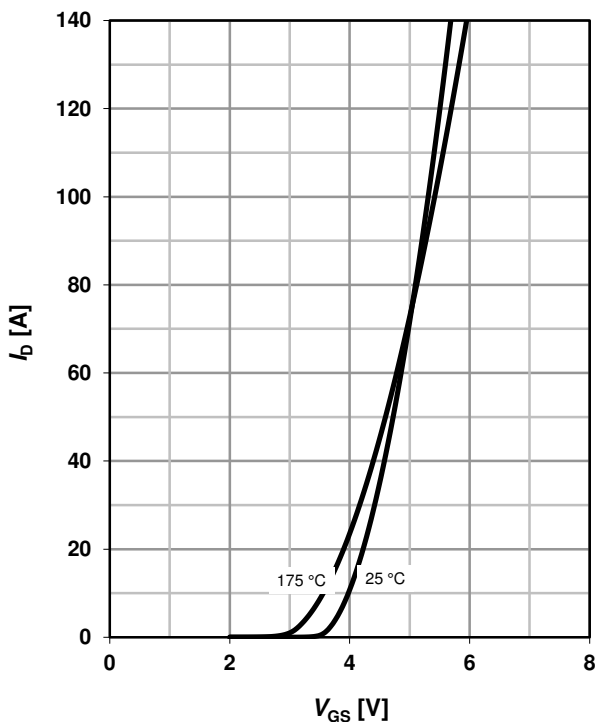
parameter:  $V_{GS}$



**7 Typ. transfer characteristics**

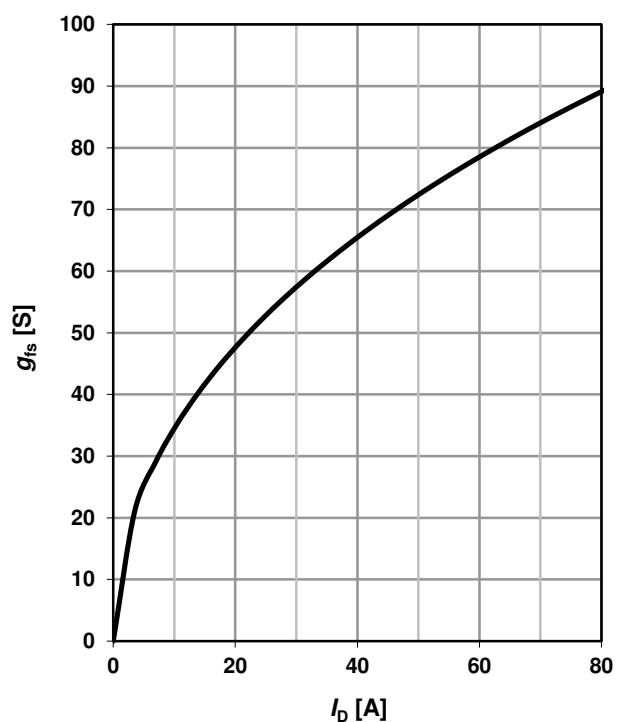
$I_D=f(V_{GS}); |V_{DS}|>2I_D R_{DS(on)max}$

parameter:  $T_j$



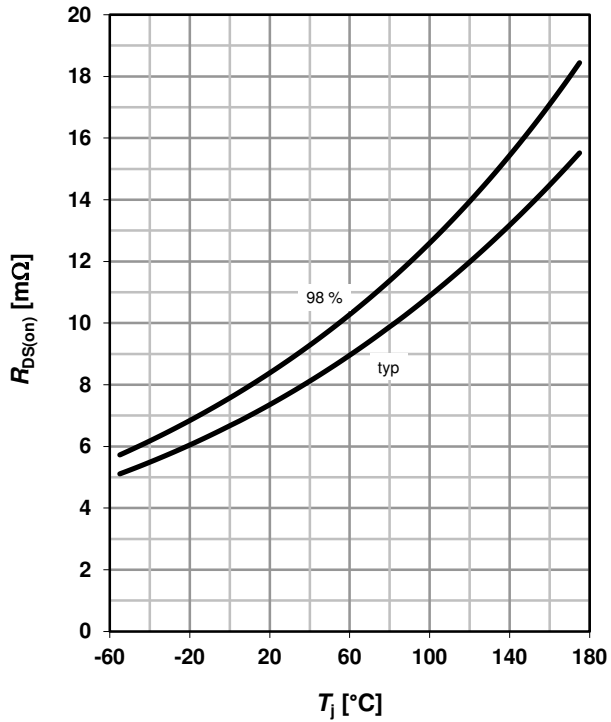
**8 Typ. forward transconductance**

$g_{fs}=f(I_D); T_j=25\text{ }^\circ\text{C}$



**9 Drain-source on-state resistance**

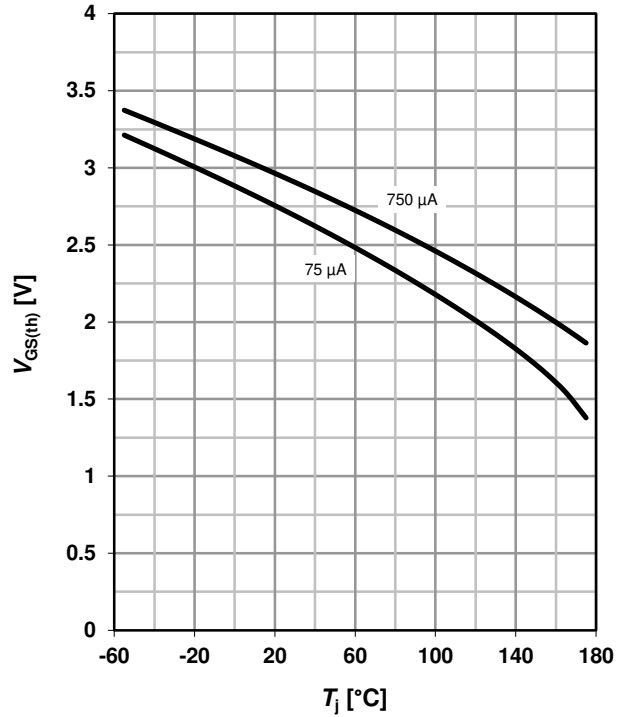
$R_{DS(on)}=f(T_j); I_D=45\text{ A}; V_{GS}=10\text{ V}$



**10 Typ. gate threshold voltage**

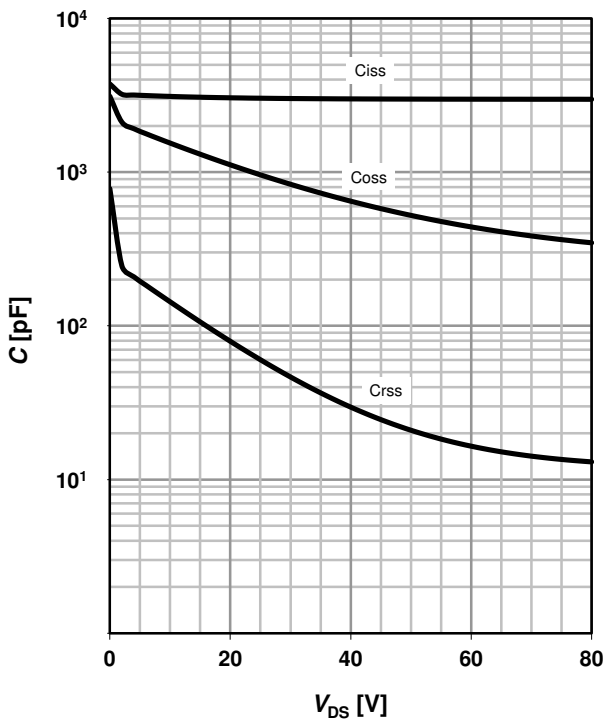
$V_{GS(th)}=f(T_j); V_{GS}=V_{DS}$

parameter:  $I_D$



**11 Typ. capacitances**

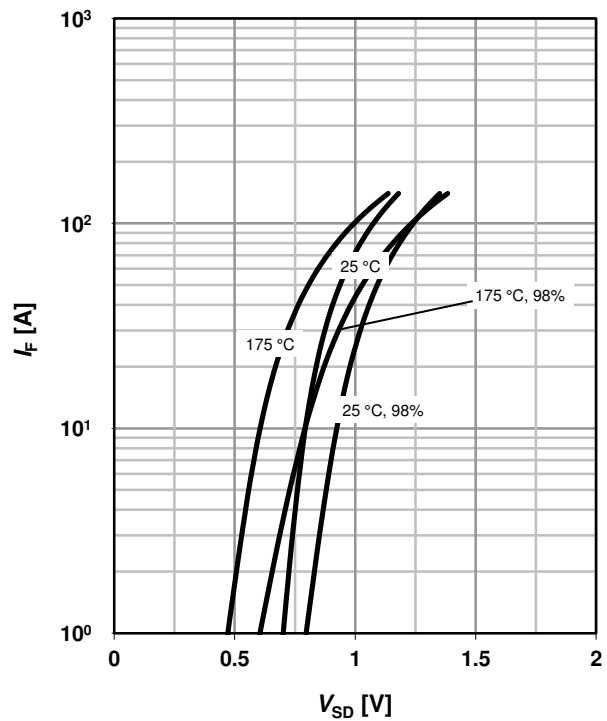
$C=f(V_{DS}); V_{GS}=0\text{ V}; f=1\text{ MHz}$



**12 Forward characteristics of reverse diode**

$I_F=f(V_{SD})$

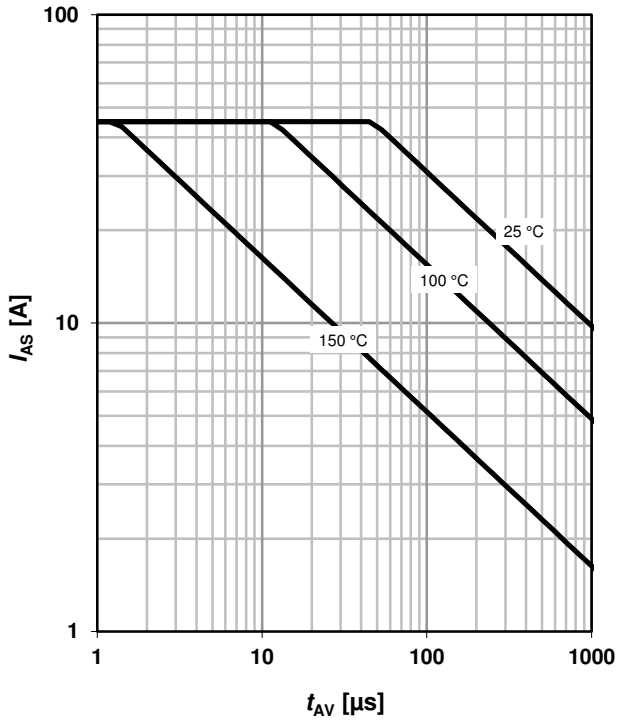
parameter:  $T_j$



**13 Avalanche characteristics**

$I_{AS}=f(t_{AV}); R_{GS}=25 \Omega$

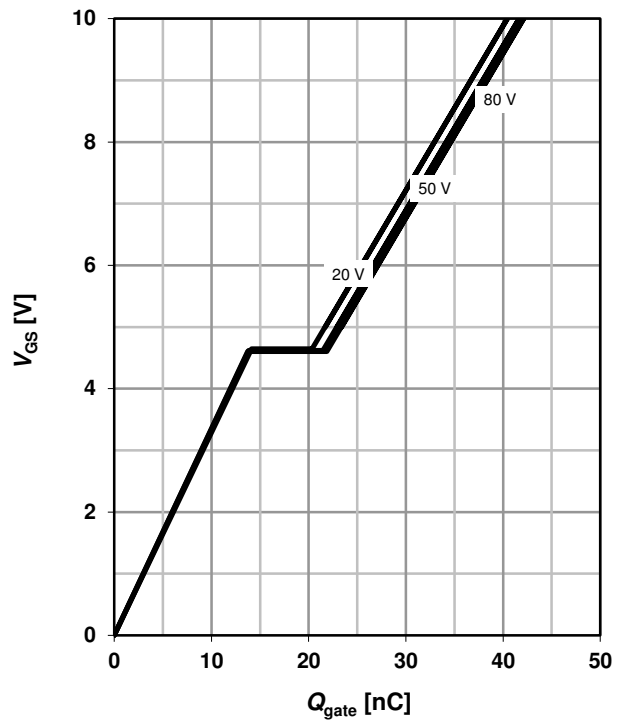
parameter:  $T_{j(start)}$



**14 Typ. gate charge**

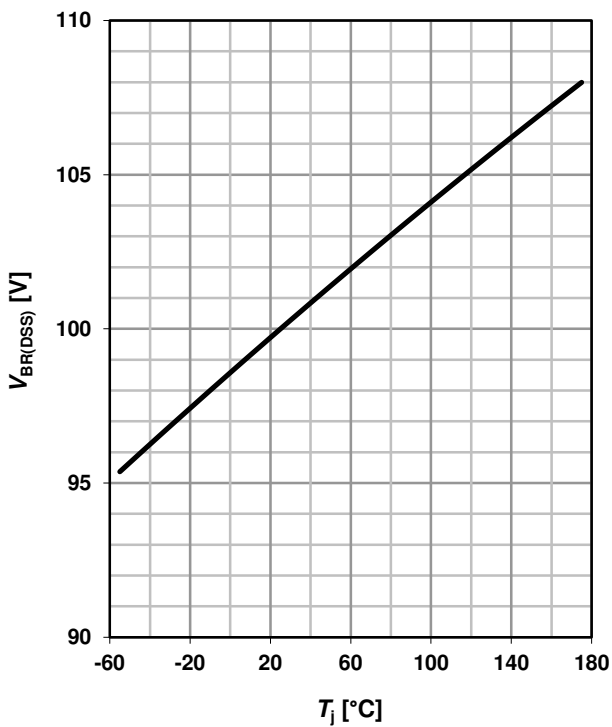
$V_{GS}=f(Q_{gate}); I_D=45 \text{ A pulsed}$

parameter:  $V_{DD}$

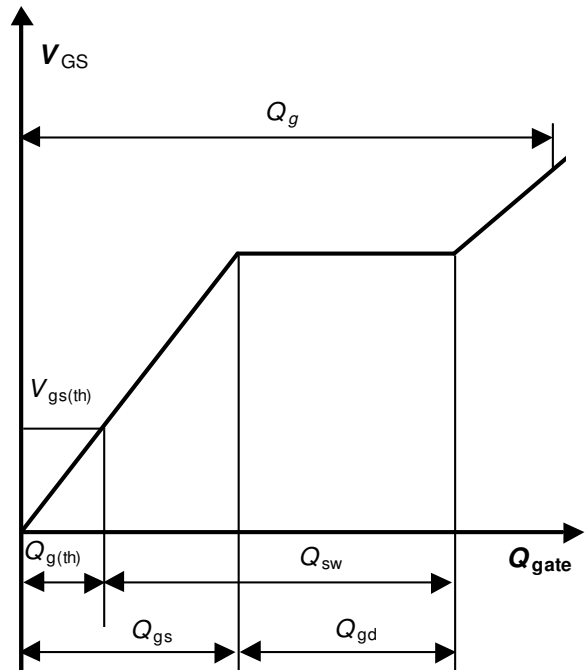


**15 Drain-source breakdown voltage**

$V_{BR(DSS)}=f(T_j); I_D=1 \text{ mA}$

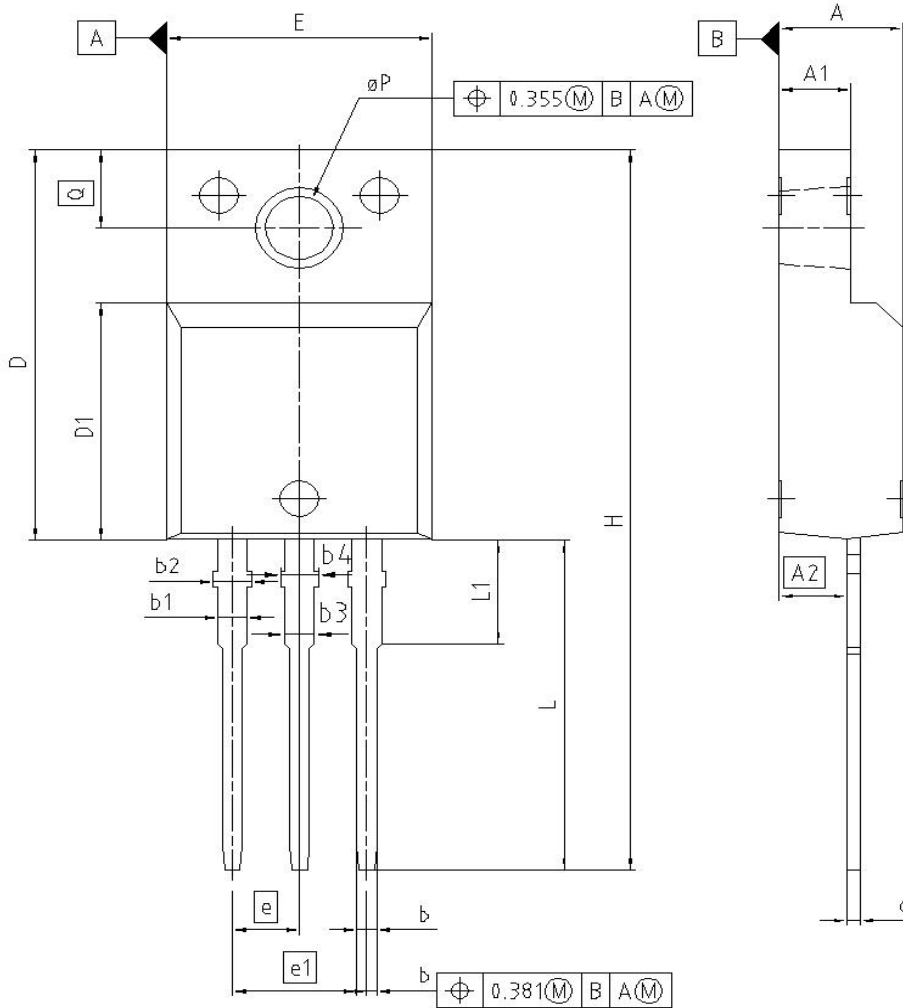


**16 Gate charge waveforms**





PG-TO220-FP



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.55	4.85	0.179	0.191
A1	2.55	2.85	0.100	0.112
A2	2.42	2.72	0.095	0.107
b	0.65	0.85	0.026	0.033
b1	0.95	1.33	0.037	0.052
b2	0.95	1.51	0.037	0.059
b3	0.65	1.33	0.026	0.052
b4	0.65	1.51	0.026	0.059
c	0.40	0.63	0.016	0.025
D	15.85	16.15	0.624	0.636
D1	9.53	9.83	0.375	0.387
E	10.35	10.65	0.407	0.419
e	2.54		0.100	
e1	5.08		0.200	
N	3		3	
H	29.45	29.75	1.159	1.171
L	13.45	13.75	0.530	0.541
L1	3.15	3.45	0.124	0.136
øP	2.95	3.20	0.116	0.126
Q	3.15	3.50	0.124	0.138

REFERENCE  
...

SCALE  
0 2.5 5mm

EUROPEAN PROJECTION

ISSUE DATE  
08-01-2007

FILE  
TO220\_2

## Revision History

IPA086N10N3 G

**Revision: 2015-08-27, Rev. 2.4**

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.4	2015-08-27	Update features: "Fully isolated package..."

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